

# TYPES 2N1047, 2N1048, 2N1049, 2N1050 N-P-N DIFFUSED JUNCTION SILICON TRANSISTORS



TYPES 2N1047, 2N1048, 2N1049, 2N1050  
 BULLETIN No. DL-S-970, AUGUST, 1958

**40 watts at 25°C with infinite heat sink**  
**Stud mounted for maximum thermal efficiency**  
**- 65°C to + 200°C operating and storage range**  
**80 and 120 volt breakdown voltage**



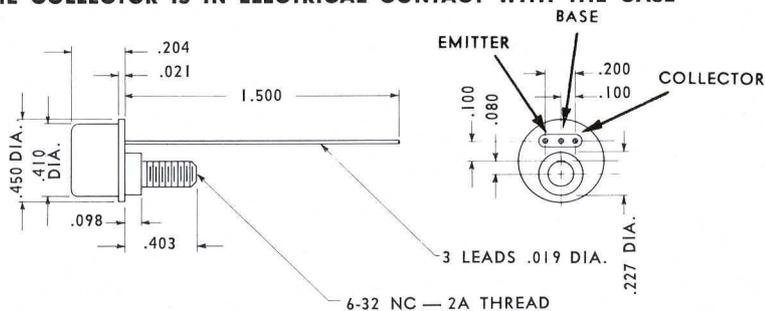
**qualification testing**

Each unit is heat cycled from - 65°C to + 175°C for ten cycles, and then humidity cycled at temperature from - 65°C to + 75°C in air at 95% relative humidity for four cycles. The hermetic seal is tested by subjecting immersed units to hydraulic pressure. Each unit is thoroughly tested to determine the electrical design characteristics. Production samples are life tested periodically to determine the effects of storage and dissipation and ensure maximum attainable reliability.

**mechanical data**

The transistor is contained in a stud mounted welded package with glass-to-metal hermetic seal between case and leads. Approximate weight is 2.0 grams.

**THE COLLECTOR IS IN ELECTRICAL CONTACT WITH THE CASE**



DIMENSIONS ARE MAXIMUM IN INCHES UNLESS OTHERWISE SPECIFIED

**maximum ratings**

Collector Voltage referred to base or emitter at 25°C (Breakdown voltages are indicated below)  
 Collector Dissipation at 25°C. (case temperature) \* . . . . . 40 W  
 Junction Temperature (maximum range) . . . . . -65°C to +200°C

\*Derate 228 mW/°C increase in case temperature within range of 25°C to 200°C

**maximum and minimum design characteristics at T<sub>c</sub> = 25°C**

| PARAMETER                                 | TEST CONDITIONS                                   | 2N1047    | 2N1048    | 2N1049    | 2N1050    | unit |
|---|---|-----------|-----------|-----------|-----------|------|
|   |   | min. max. | min. max. | min. max. | min. max. |      |
| BV <sub>CEX</sub> Breakdown Voltage       | I <sub>C</sub> = 250 μA V <sub>BE</sub> = - 1.5 V | 80        | 120       | 80        | 120       | V    |
| BV <sub>EBO</sub> Breakdown Voltage       | I <sub>E</sub> = 250 μA I <sub>C</sub> = 0        | 10        | 10        | 10        | 10        | V    |
| I <sub>CBO</sub> Collector Cutoff Current | V <sub>CB</sub> = 30V I <sub>E</sub> = 0          | 15        | 15        | 15        | 15        | μA   |
| h <sub>FE</sub> Current Transfer Ratio†   | V <sub>CE</sub> = 10V I <sub>C</sub> = 200mA      | 12 36     | 12 36     | 30 90     | 30 90     | —    |
| h <sub>IE</sub> Input Impedancet          | V <sub>CE</sub> = 10V I <sub>B</sub> = 8mA        | 500       | 500       | 500       | 500       | ohm  |
| R <sub>CS</sub> Saturation Resistancet    | I <sub>C</sub> = 200 mA I <sub>B</sub> = 40mA     | 15        | 15        | 15        | 15        | ohm  |
| V <sub>BE</sub> Base Voltage †            | V <sub>CE</sub> = 15V I <sub>C</sub> = 500mA      | 10        | 10        | 10        | 10        | V    |

† Semiautomatic testing is facilitated by using pulse techniques to measure these parameters. A 300-microsecond pulse (approximately 2% duty cycle) is utilized. Thus, the unit can be tested under maximum current conditions without a significant increase in junction temperature, even though no heat sink is used. The parameter values obtained in this manner are particularly pertinent for switching circuit design and, in general, indicate the true capabilities of the device.

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